

# IRG4PSC71UDPbF

INSULATED GATE BIPOLAR TRANSISTOR WITH  
ULTRAFAST SOFT RECOVERY DIODE

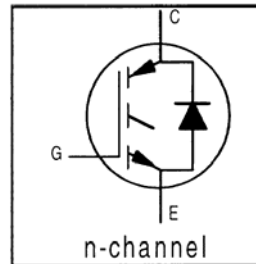
UltraFast CoPack IGBT

## Features

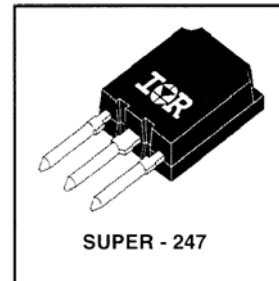
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency (minimum switching and conduction losses) than prior generations
- IGBT co-packaged with HEXFRED ultrafast, ultrasoft recovery anti-parallel diodes for use in bridge configurations
- Industry-benchmark Super-247 package with higher power handling capability compared to same footprint TO-247
- Creepage distance increased to 5.35mm
- Lead-Free

## Benefits

- Generation 4 IGBT's offer highest efficiencies available
- Maximum power density, twice the power handling of TO-247, less space than TO-264
- IGBTs optimized for specific application conditions
- HEXFRED diodes optimized for performance with IGBTs
- Cost and space saving in designs that require multiple, paralleled IGBTs



|                                   |
|-----------------------------------|
| $V_{CES} = 600V$                  |
| $V_{CE(on)} \text{ typ.} = 1.67V$ |
| @ $V_{GE} = 15V, I_C = 60A$       |



## Absolute Maximum Ratings

|                           | Parameter                                   | Max.                              | Units      |
|---------------------------|---|-----------------------------------|------------|
| $V_{CES}$                 | Collector-to-Emitter Voltage                | 600                               | V          |
| $I_C @ T_C = 25^\circ C$  | Continuous Collector Current                | 85 <sup>⑤</sup>                   | A          |
| $I_C @ T_C = 100^\circ C$ | Continuous Collector Current                | 60                                |            |
| $I_{CM}$                  | Pulsed Collector Current <sup>①</sup>       | 200                               |            |
| $I_{LM}$                  | Clamped Inductive Load Current <sup>②</sup> | 200                               |            |
| $I_F @ T_C = 100^\circ C$ | Diode Continuous Forward Current            | 60                                |            |
| $I_{FM}$                  | Diode Maximum Forward Current               | 350                               |            |
| $V_{GE}$                  | Gate-to-Emitter Voltage                     | $\pm 20$                          | V          |
| $P_D @ T_C = 25^\circ C$  | Maximum Power Dissipation                   | 350                               | W          |
| $P_D @ T_C = 100^\circ C$ | Maximum Power Dissipation                   | 140                               |            |
| $T_J$                     | Operating Junction and                      | -55 to +150                       | $^\circ C$ |
| $T_{STG}$                 | Storage Temperature Range                   |                                   |            |
|                           | Soldering Temperature, for 10 sec.          | 300 (0.063 in. (1.6mm) from case) |            |

## Thermal Resistance\ Mechanical

|                 | Parameter                                 | Min.      | Typ.     | Max. | Units        |
|-----------------|---|-----------|----------|------|--------------|
| $R_{\theta JC}$ | Junction-to-Case - IGBT                   | —         | —        | 0.36 | $^\circ C/W$ |
| $R_{\theta JC}$ | Junction-to-Case - Diode                  | —         | —        | 0.69 |              |
| $R_{\theta CS}$ | Case-to-Sink, flat, greased surface       | —         | 0.24     | —    |              |
| $R_{\theta JA}$ | Junction-to-Ambient, typical socket mount | —         | —        | 38   |              |
|                 | Recommended Clip Force                    | 20.0(2.0) | —        | —    | N (kgf)      |
|                 | Weight                                    | —         | 6 (0.21) | —    | g (oz)       |

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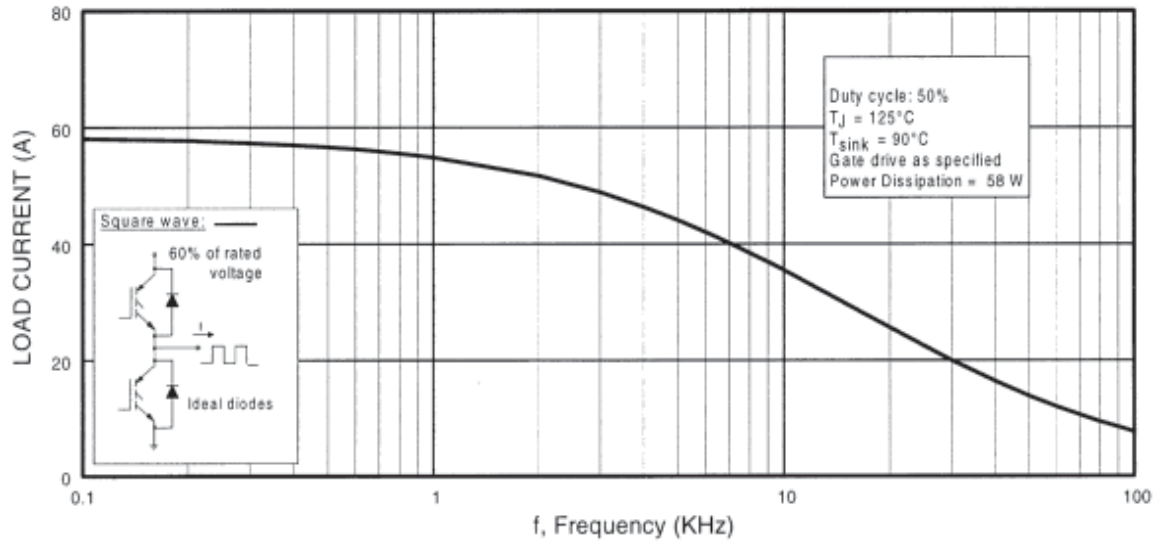
International  
IR Rectifier

## Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

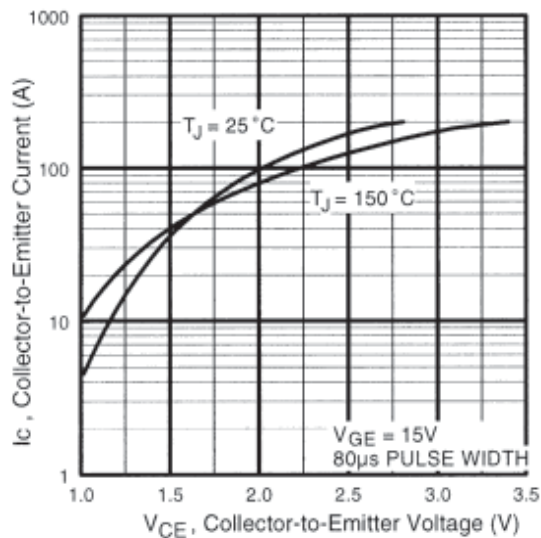
|                                 | Parameter   | Min. | Typ. | Max.      | Units   | Conditions                                      |
|---------------------------------|---|------|------|-----------|---------|---|
| $V_{(BR)CES}$                   | Collector-to-Emitter Breakdown Voltage <sup>③</sup> | 600  | —    | —         | V       | $V_{GE} = 0V, I_C = 250\mu A$                   |
| $\Delta V_{(BR)CES}/\Delta T_J$ | Temperature Coeff. of Breakdown Voltage             | —    | 0.39 | —         | V/°C    | $V_{GE} = 0V, I_C = 10mA$                       |
| $V_{CE(on)}$                    | Collector-to-Emitter Saturation Voltage             | —    | 1.67 | 2.0       | V       | $I_C = 60A, V_{GE} = 15V$<br>See Fig. 2, 5      |
|                                 |   | —    | 1.95 | —         |         |   |
|                                 |   | —    | 1.71 | —         |         |   |
| $V_{GE(th)}$                    | Gate Threshold Voltage                              | 3.0  | —    | 6.0       |         | $V_{CE} = V_{GE}, I_C = 250\mu A$               |
| $\Delta V_{GE(th)}/\Delta T_J$  | Temperature Coeff. of Threshold Voltage             | —    | -13  | —         | mV/°C   | $V_{CE} = V_{GE}, I_C = 1.5mA$                  |
| $g_{fe}$                        | Forward Transconductance <sup>②</sup>               | 47   | 70   | —         | S       | $V_{CE} = 50V, I_C = 60A$                       |
| $I_{CES}$                       | Zero Gate Voltage Collector Current                 | —    | —    | 500       | $\mu A$ | $V_{GE} = 0V, V_{CE} = 600V$                    |
|                                 |   | —    | —    | 13        | mA      | $V_{GE} = 0V, V_{CE} = 600V, T_J = 150^\circ C$ |
| $V_{FM}$                        | Diode Forward Voltage Drop                          | —    | 1.4  | 1.7       | V       | $I_C = 60A$<br>See Fig. 13                      |
|                                 |   | —    | 1.3  | —         |         |   |
| $I_{GES}$                       | Gate-to-Emitter Leakage Current                     | —    | —    | $\pm 100$ | nA      | $V_{GE} = \pm 20V$                              |

## Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

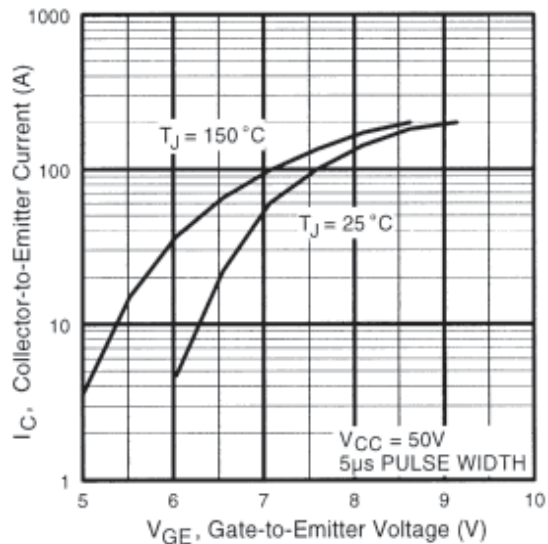
|                                  | Parameter                           | Min. | Typ. | Max. | Units      | Conditions  |
|----------------------------------|-------------------------------------|------|------|------|------------|---|
| $Q_g$                            | Total Gate Charge (turn-on)         | —    | 340  | 520  | nC         | $I_C = 60A$<br>$V_{CC} = 400V$<br>$V_{GE} = 15V$<br>See Fig. 8  |
| $Q_{ge}$                         | Gate - Emitter Charge (turn-on)     | —    | 44   | 66   |            |   |
| $Q_{gc}$                         | Gate - Collector Charge (turn-on)   | —    | 160  | 240  |            |   |
| $t_{d(on)}$                      | Turn-On Delay Time                  | —    | 90   | —    | ns         | $T_J = 25^\circ C$<br>$I_C = 60A, V_{CC} = 480V$<br>$V_{GE} = 15V, R_G = 5.0\Omega$<br>Energy losses include "tail" and diode reverse recovery.<br>See Fig. 9, 10, 11, 18 |
| $t_r$                            | Rise Time                           | —    | 94   | —    |            |   |
| $t_{d(off)}$                     | Turn-Off Delay Time                 | —    | 245  | 368  |            |   |
| $t_f$                            | Fall Time                           | —    | 110  | 167  |            |   |
| $E_{on}$                         | Turn-On Switching Loss              | —    | 3.26 | —    | mJ         | See Fig. 9, 10, 11, 18  |
| $E_{off}$                        | Turn-Off Switching Loss             | —    | 2.27 | —    |            |   |
| $E_{ts}$                         | Total Switching Loss                | —    | 5.53 | 7.2  |            |   |
| $t_{d(on)}$                      | Turn-On Delay Time                  | —    | 91   | —    | ns         | $T_J = 150^\circ C$ , See Fig. 9, 10, 11, 18<br>$I_C = 60A, V_{CC} = 480V$<br>$V_{GE} = 15V, R_G = 5.0\Omega$<br>Energy losses include "tail" and diode reverse recovery. |
| $t_r$                            | Rise Time                           | —    | 88   | —    |            |   |
| $t_{d(off)}$                     | Turn-Off Delay Time                 | —    | 353  | —    |            |   |
| $t_f$                            | Fall Time                           | —    | 150  | —    |            |   |
| $E_{ts}$                         | Total Switching Loss                | —    | 7.1  | —    | mJ         |   |
| $L_E$                            | Internal Emitter Inductance         | —    | 13   | —    | nH         | Measured 5mm from package   |
| $C_{ies}$                        | Input Capacitance                   | —    | 7500 | —    | pF         | $V_{GE} = 0V$<br>$V_{CC} = 30V$<br>$f = 1.0MHz$<br>See Fig. 7   |
| $C_{oes}$                        | Output Capacitance                  | —    | 720  | —    |            |   |
| $C_{res}$                        | Reverse Transfer Capacitance        | —    | 93   | —    |            |   |
| $t_{rr}$                         | Diode Reverse Recovery Time         | —    | 82   | 120  | ns         | $T_J = 25^\circ C$ See Fig. 14<br>$T_J = 125^\circ C$   |
|                                  |                                     | —    | 140  | 210  |            |   |
| $I_{rr}$                         | Diode Peak Reverse Recovery Current | —    | 8.2  | 12   | A          | $T_J = 25^\circ C$ See Fig. 15<br>$T_J = 125^\circ C$   |
|                                  |                                     | —    | 13   | 20   |            |   |
| $Q_{rr}$                         | Diode Reverse Recovery Charge       | —    | 364  | 546  | nC         | $T_J = 25^\circ C$ See Fig. 16<br>$T_J = 125^\circ C$   |
|                                  |                                     | —    | 1084 | 1625 |            |   |
| $di_{(rec)M}/dt$<br>During $t_b$ | Diode Peak Rate of Fall of Recovery | —    | 328  | —    | A/ $\mu s$ | $T_J = 25^\circ C$ See Fig. 17<br>$T_J = 125^\circ C$   |
|                                  |                                     | —    | 266  | —    |            |   |



**Fig. 1 - Typical Load Current vs. Frequency**  
(Load Current =  $I_{RMS}$  of fundamental)



**Fig. 2 - Typical Output Characteristics**  
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**Fig. 3 - Typical Transfer Characteristics**

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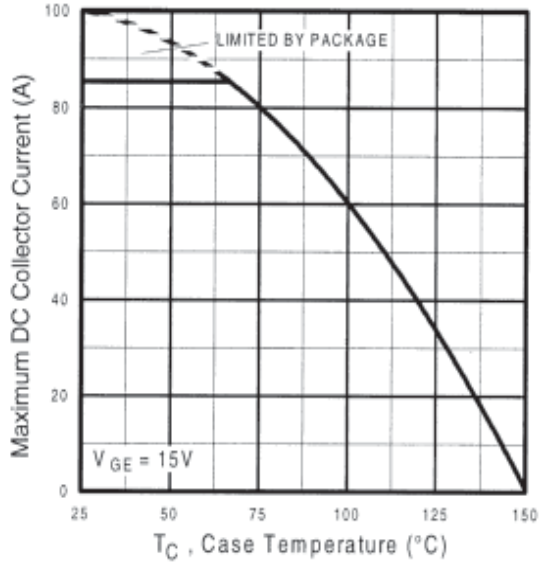


Fig. 4 - Maximum Collector Current vs. Case Temperature

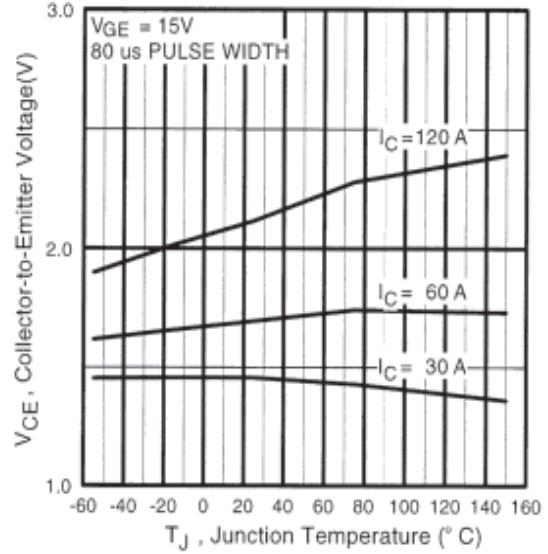


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

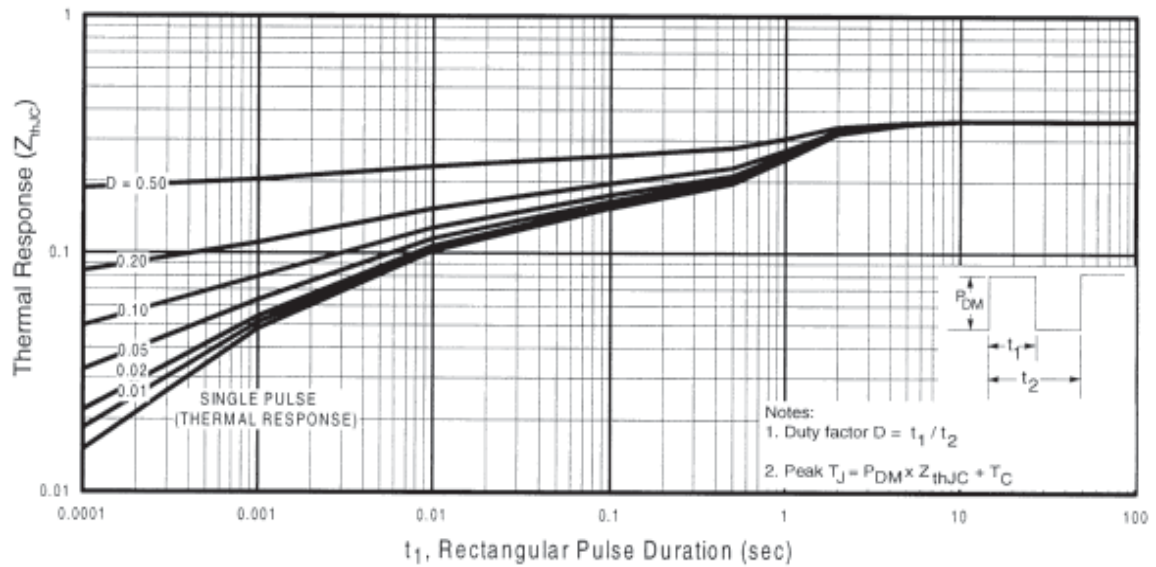
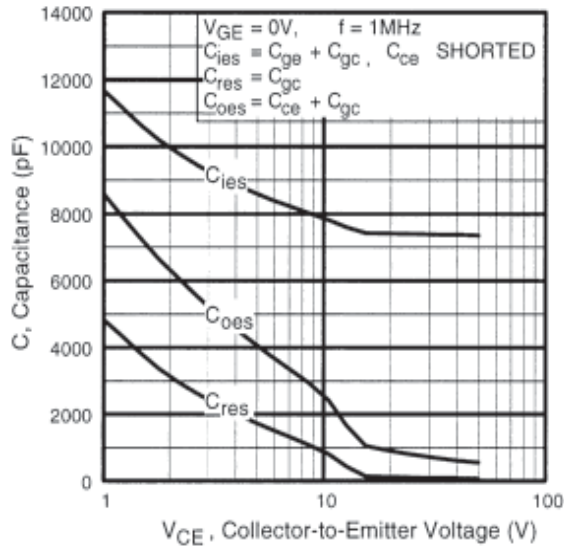
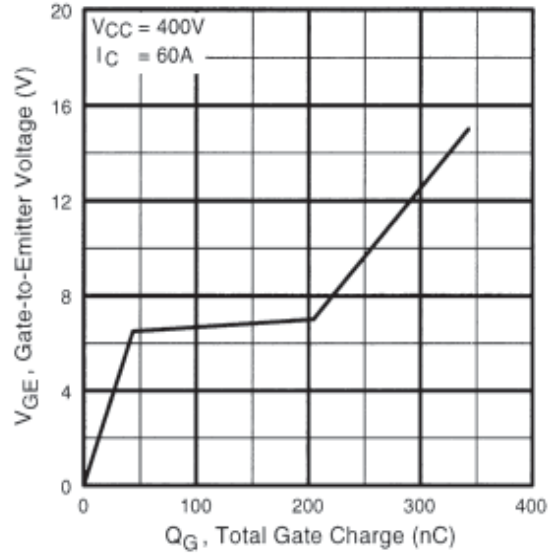


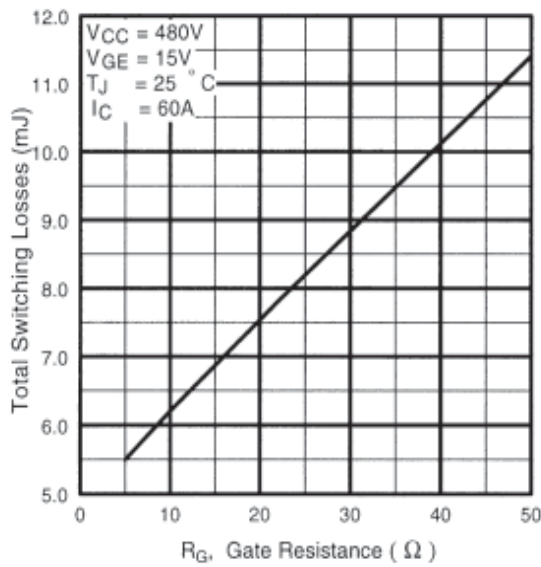
Fig. 6 - Maximum IGBT Effective Transient Thermal Impedance, Junction-to-Case



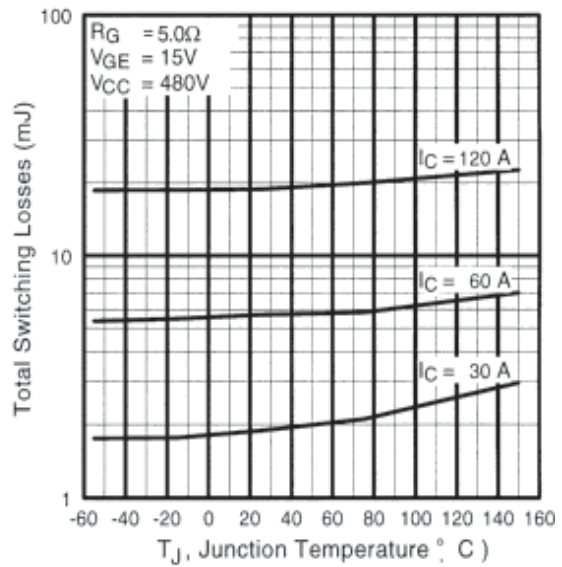
**Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage**



**Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage**



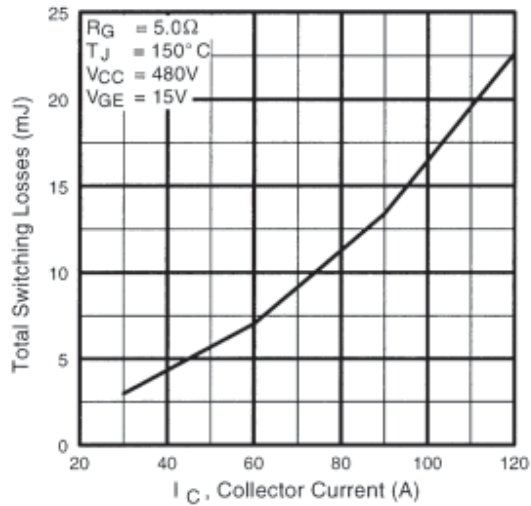
**Fig. 9 - Typical Switching Losses vs. Gate Resistance**



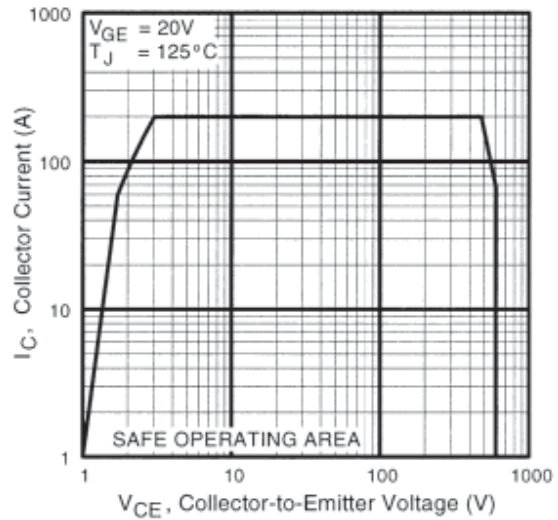
**Fig. 10 - Typical Switching Losses vs. Junction Temperature**

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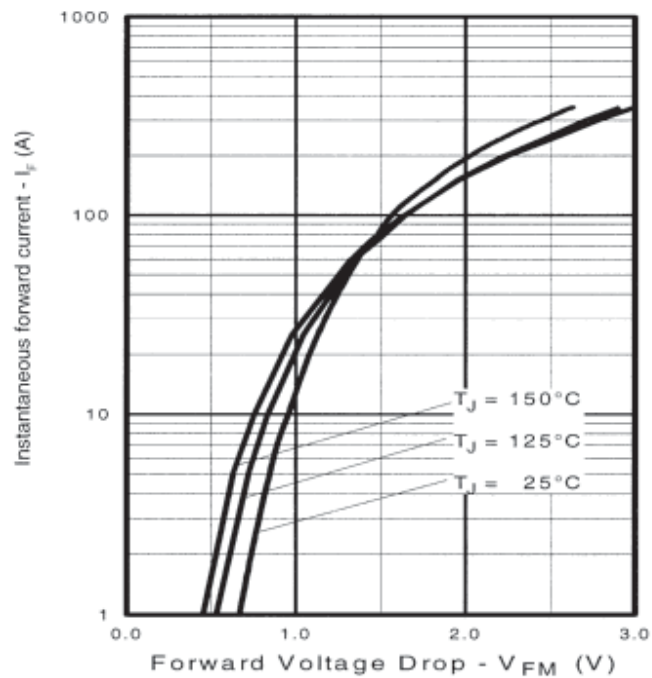
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**Fig. 11** - Typical Switching Losses vs. Collector-to-Emitter Current



**Fig. 12** - Turn-Off SOA



**Fig. 13** - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

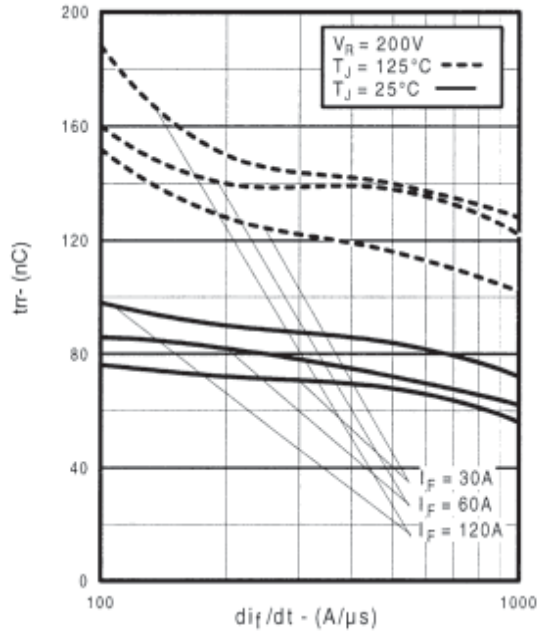


Fig. 14 - Typical Reverse Recovery vs.  $di_f/dt$

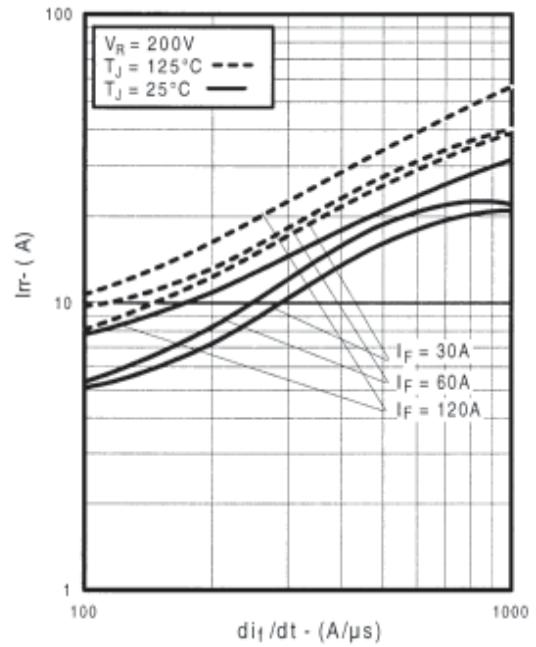


Fig. 15 - Typical Recovery Current vs.  $di_f/dt$

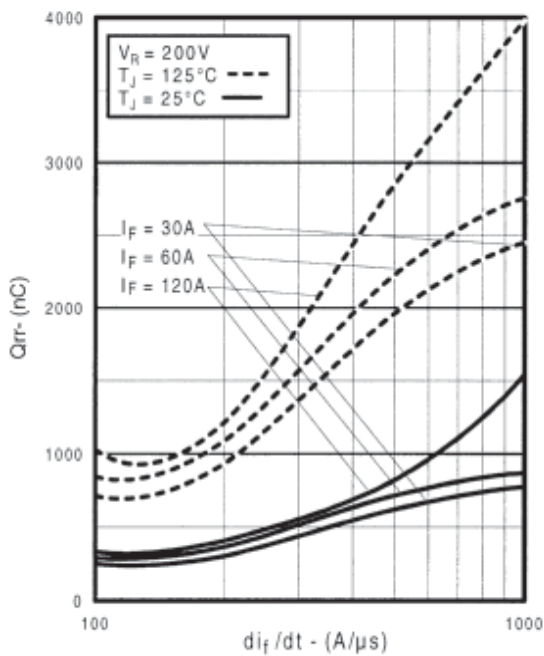


Fig. 16 - Typical Stored Charge vs.  $di_f/dt$   
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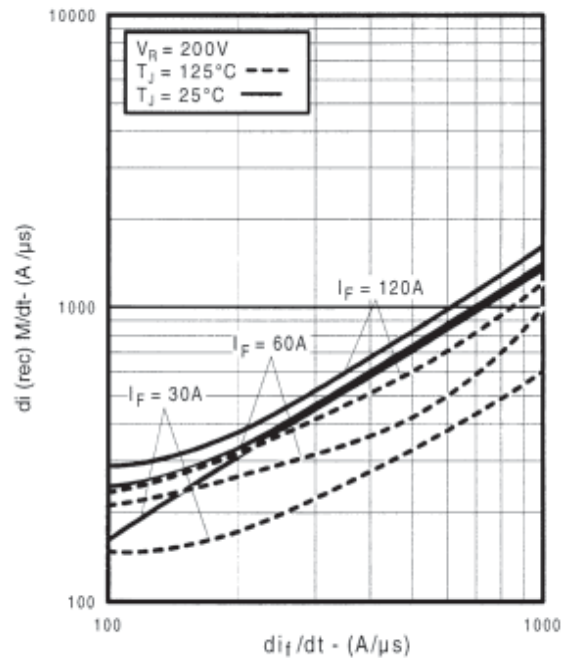
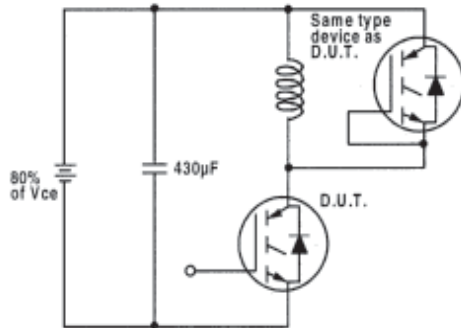


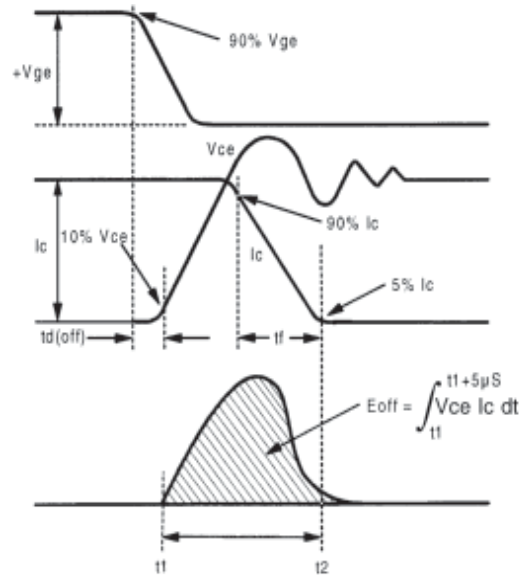
Fig. 17 - Typical  $di_{(rec)M}/dt$  vs.  $di_f/dt$

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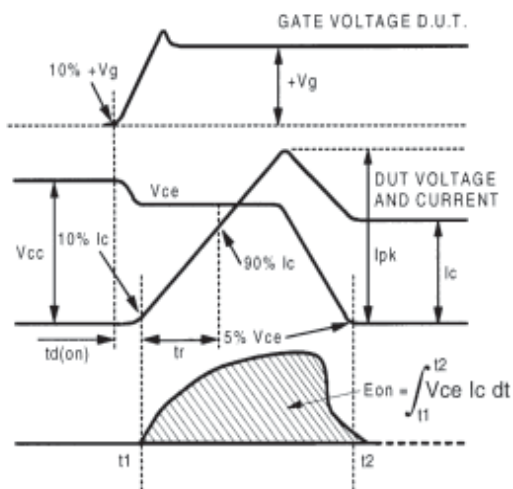
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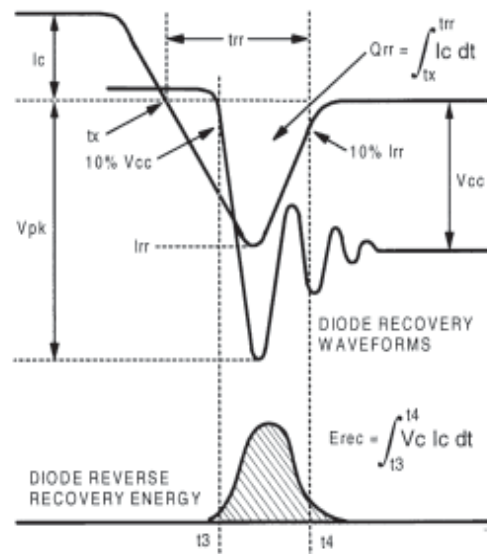
**Fig. 18a** - Test Circuit for Measurement of  $I_{LM}$ ,  $E_{on}$ ,  $E_{off}(\text{diode})$ ,  $t_{rr}$ ,  $Q_{rr}$ ,  $I_{rr}$ ,  $t_{d(on)}$ ,  $t_r$ ,  $t_{d(off)}$ ,  $t_f$



**Fig. 18b** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{off}$ ,  $t_{d(off)}$ ,  $t_f$



**Fig. 18c** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{on}$ ,  $t_{d(on)}$ ,  $t_r$



**Fig. 18d** - Test Waveforms for Circuit of Fig. 18a, Defining  $E_{rec}$ ,  $t_{tr}$ ,  $Q_{rr}$ ,  $I_{rr}$



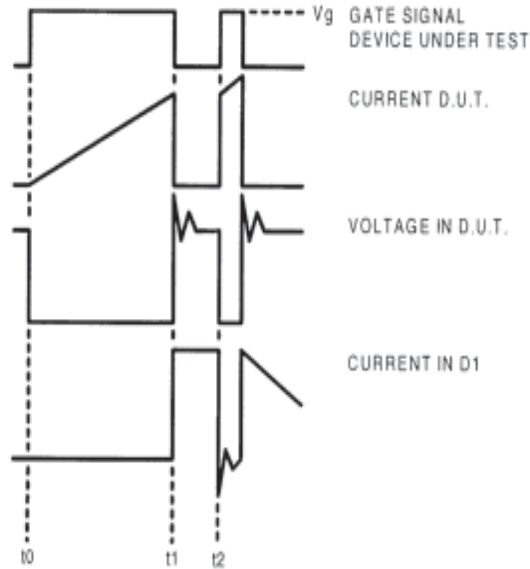


Figure 18e. Macro Waveforms for Figure 18a's Test Circuit

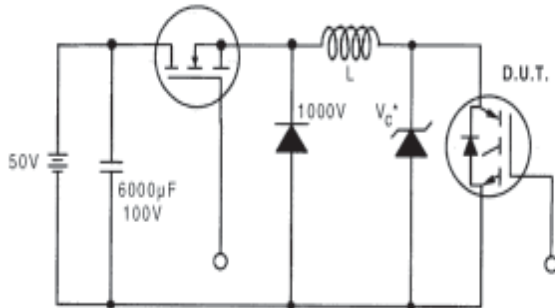


Figure 19. Clamped Inductive Load Test Circuit

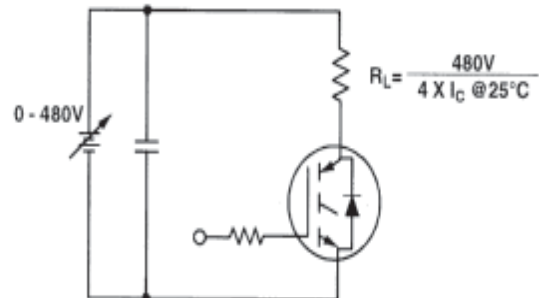


Figure 20. Pulsed Collector Current Test Circuit

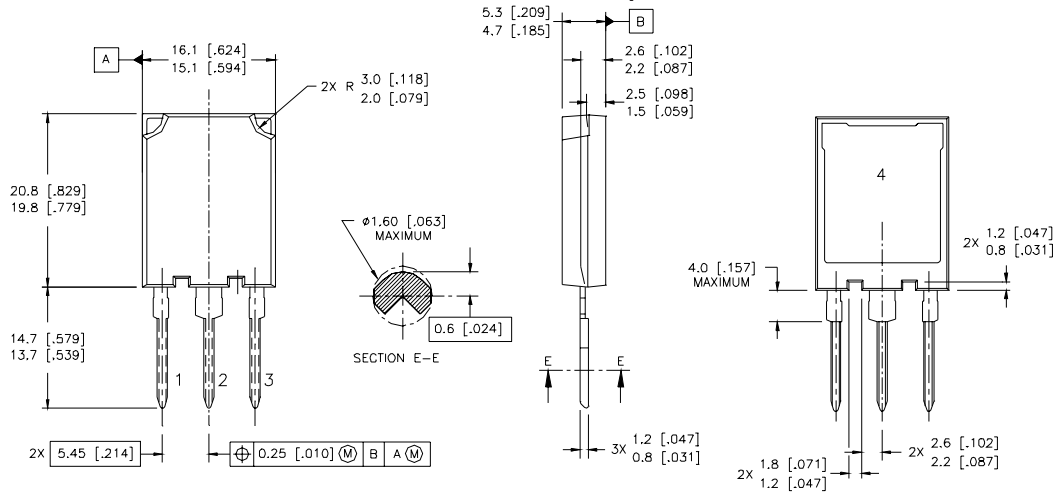
**Notes:**

- ① Repetitive rating:  $V_{GE}=20V$ ; pulse width limited by maximum junction temperature (figure 20)
- ②  $V_{CC}=80\%(V_{CES})$ ,  $V_{GE}=20V$ ,  $L=10\mu H$ ,  $R_G=5.0\Omega$  (figure 19)
- ③ Pulse width  $\leq 80\mu s$ ; duty factor  $\leq 0.1\%$
- ④ Pulse width  $5.0\mu s$ , single shot
- ⑤ Current limited by the package, (Die current = 100A)

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## Case Outline and Dimensions — Super-247

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**NOTES:**

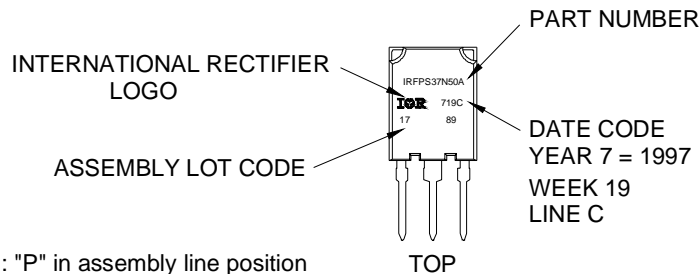
1. DIMENSIONS & TOLERANCING PER ASME Y14.5M-1994
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETRES [INCHES]

**LEAD ASSIGNMENTS**

| MOSFET     | IGBT          |
|------------|---------------|
| 1 - GATE   | 1 - GATE      |
| 2 - DRAIN  | 2 - COLLECTOR |
| 3 - SOURCE | 3 - EMITTER   |
| 4 - DRAIN  | 4 - COLLECTOR |

## Super-247 (TO-274AA) Part Marking Information

EXAMPLE: THIS IS AN IRFPS37N50A WITH  
ASSEMBLY LOT CODE 1789  
ASSEMBLED ON WW 19, 1997  
IN THE ASSEMBLY LINE "C"



Note: "P" in assembly line position indicates "Lead-Free"

Data and specifications subject to change without notice.

International  
**IR** Rectifier

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